

INSTALLATION OF MEMORY CHIPS: (OPTION B)

STEP 1. AFTER MAKING SURE CHIP PAD AREA IS FREE FROM FLUX AND LOCTITE-422 RESIDUE, APPLY LIBERAL AMOUNT OF FRESH FLUX TO PADS AND POSITION NEW MEMORY CHIP, MAKING SURE THAT THE CHIPS LEGLESS LEADS AND THE BOARD PADS LINE UP AND THAT THE CHIP IS CENTERED AS MUCH AS POSSIBLE.

STEP 2. USING THE 600 DEGREE IRON, TOUCH THE IRON AGAINST ANY PAD, AS CLOSE AS POSSIBLE TO THE CHIP WITHOUT TOUCHING THE CHIP, AND APPLY SOME SOLDER. WAIT FOR THE SOLDER TO FLOW AND WICK UP UNDER THE CHIP. REPEAT THIS STEP ON THE PAD HALFWAY AROUND THE CHIP. THIS WILL HOLD THE CHIP IN PLACE WHILE YOU SOLDER THE REMAINING PADS. REFER TO FIGURE M-5.

STEP 3. SOLDER THE REMAINING PADS.

**** NOTE: IT IS NOT NECESSARY TO FLOW THE SOLDER ALL THE WAY UP THE PLATED PORTION OF THE LEGLESS LEAD ON THE VERTICAL SIDES OF THE CHIP. AS LONG AS THE LEADS WERE TINNED ON THE UNDERSIDE OF THE CHIP AND AT LEAST PARTIALLY UP THE VERTICAL SIDES, ALLOWING FOR A MINIMAL FILLET OF SOLDER BETWEEN THE PADS AND CHIP SIDES, YOU SHOULD HAVE NO PROBLEMS. ALSO, MAKE SURE THAT THE SOLDER FLOW HAS ENOUGH TIME TO WICK UP UNDER THE CHIP WHILE REMEMBERING NOT TO BURN A HOLE IN THE BOARD. HAVE FUN. REFER TO FIGURE M-6.

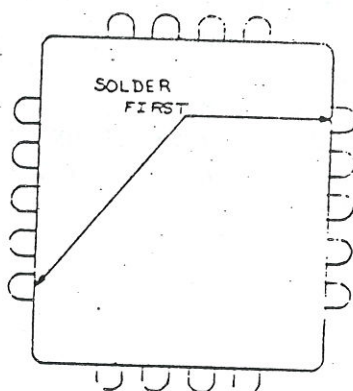


FIG. M-5

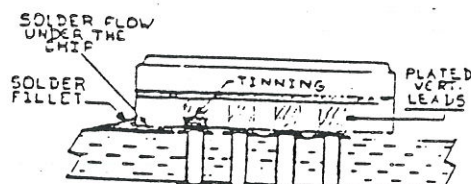


FIG. M-6